Title (en)

HARD-SOLDERING METHOD AND DEVICE

Title (de)

VERFAHREN UND VORRICHTUNG ZUM HARTLÖTEN

Title (fr)

PROCEDE ET DISPOSITIF DE BRASAGE

Publication

EP 1750883 A1 20070214 (DE)

Application

EP 05740502 A 20050520

Priority

- CH 2005000287 W 20050520
- CH 9282004 A 20040601

Abstract (en)

[origin: WO2005118196A1] To hard-solder parts to be joined (2) along a common joint, the parts are heated by a heat source e.g. a laser beam (3). Fused solder (7) that is stored in a container (6) is then introduced into the joint. Joints can be rapidly filled with solder in this manner and the solidified solder surface is practically devoid of pores, thus permitting the priming or painting of said parts without the need for subsequent treatment.

IPC 8 full level

B23K 1/005 (2006.01); **B23K 3/03** (2006.01); **B23K 3/06** (2006.01)

CPC (source: EP KR US)

B23K 1/00 (2013.01 - KR); **B23K 1/005** (2013.01 - KR); **B23K 1/0056** (2013.01 - EP US); **B23K 3/03** (2013.01 - KR); **B23K 3/0353** (2013.01 - EP US); **B23K 3/06** (2013.01 - KR); **B23K 3/0607** (2013.01 - EP US); B23K 2101/006 (2018.07 - EP US)

Citation (search report)

See references of WO 2005118196A1

Designated contracting state (EPC)

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